BROADCOM

PA-302382

Product Advisory

Issue Date: December 5, 2025

Change Description:

Adding additional assembly location – ASE Taiwan

Parts Affected:

Part Number	PKG	Current Assy Site	Second source Assy Site
BCM5719A1KFBG	FBGA 17X17	ATX (CN)	ASEKH (TW)
BCM5720LA0KPBG	PBGA 23X23	ATX (CN)	ASEKH (TW)

Description and Extent of Change:

Adding ASE Taiwan as an additional assembly location. There is no impact or change to the current assembly location and supplier.

Reasons for Change:

Adding an additional assembly location to ensure supply chain continuity.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There is no impact or change to the silicon design, fabrication, or electrical performance of the bare die part.

Additional supplier location will adopt same assembly process, flow, and wafer dicing recipe to ensure no impact to device's fit, form, function, quality, and reliability.

Effective Date of Change:

Product shipments with this change will begin after March 1, 2026. Timing of shipments will vary depending on customer demand and inventory levels.

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice within 30 days of delivery. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.